LISTING OF CLAIMS:

10 / 511315 DT04 Rec'd PCT/PT0 1 5 OCT 2004

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) A process for producing a coated substrate which has having at least one metallic surface, wherein comprising:

depositing an the evaporation-coating glass is deposited in structured form at least on the at least one metallic surface, and the substrate is coated with an evaporation-coating glass at least on the metallic surface.

- 2. (Currently amended) The process as claimed in claim 1, wherein the evaporation-coating glass is applied deposited by evaporation coating through electron beam evaporation.
- 3. (Currently amended) The A process as claimed in one of the preceding claims, which includes the steps of for producing a coated substrate having a metallic surface, comprising:

producing at least one negatively structured first coating
on the metallic surface[[,]];

depositing an in particular hermetic evaporation-coating glass layer on the metallic surface which has been provided with the first coating[[,]]; and

at least partially removing the <u>at least one negatively</u> structured first coating and the <u>hermetic</u> evaporation-coating glass layer on top of it <u>thereon</u>.

- 4. (Currently amended) The process as claimed in claim 3, wherein the step of producing a the at least one negatively structured first coating on the metallic surface comprises the step of uncovering regions of the at least one metallic surface which is that are to be coated.
- 5. (Currently amended) The process as claimed in either of claims 3 and 4 claim 3, wherein the step of producing a the at least one negatively structured first coating comprises the step of resist-coating or printing, in particular of resist-coating by means of spin coating and/or spraying and/or electrodeposition and printing by means of screen-printing and/or ink jet printing processes to form a first coating.
- 6. (Currently amended) The process as claimed in one of claims 3 to 5 claim 3, wherein the step of at least partially removing the at least one negatively structured first coating comprises the step of lifting off regions of the at least one hermetic evaporation-coating glass layer which cover the first coating.
- 7. (Currently amended) The process as claimed in one of claims 3 to 6 claim 3, wherein the hermetic evaporation-coating glass layer is deposited with a thickness which that is less than the thickness of the at least one negatively structured first coating.
- 8. (Currently amended) The process as claimed in one of claims 3 to 7, which includes claim 3, further comprising the step of at least partially uncovering the at least one negatively structured first coating.

- 9. (Currently amended) The process as claimed in claim 8, wherein the step of at least partially uncovering the at least one negatively structured first coating comprises the step of planarizing the coated metallic surface having the at least one negatively structured first coating and the hermetic evaporation-coating glass layer thereon.
- or 9, wherein the step of partially uncovering the at least one negatively structured first coating comprises the step of mechanically removal of removing material, in particular by means of a process selected from the group consisting of grinding, and/or lapping, and/or polishing.
- 11. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein depositing the hermetic evaporation-coating glass layer is applied by comprises evaporation coating through a mask.
- 12. (Currently amended) The process as claimed in one of the preceding claims, wherein claim 3, further comprising depositing at least two hermetic evaporation-coating glass layers are deposited on the metallic substrate.
- 13. (Currently amended) The process as claimed in one of the preceding claims claim 12, wherein the at least two evaporation-coating glass layers comprise with different compositions are applied.

- 14. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein the hermetic evaporation-coating glass layer is applied deposited with a thickness in a range from 0.01 μ m to 1 mm.
- 15. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein the composition of the hermetic evaporation-coating glass layer has a composition that is varied while the latter is being applied deposited.
- 16. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein depositing the hermetic evaporation-coating glass layer comprises co-evaporating the coating with an evaporation-coating glass layer comprises the deposition of evaporation-coating material from at least two sources by co-evaporation.
- 17. (Currently amended) The process as claimed in one of the preceding claims, wherein claim 3, further comprising heating the metallic substrate is heated during coating with deposition of the hermetic evaporation-coating glass layer.
- 18. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein the pressure during coating depositing the hermetic evaporation-coating glass layer occurs at a pressure that is at most 10^{-4} mbar.
- 19. (Currently amended) The process as claimed in one of the preceding claims, wherein claim 3, further comprising structuring the hermetic evaporation-coating glass layer is structured following the coating depositing operation.

- 20. (Currently amended) The process as claimed in claim 19, wherein structuring the hermetic evaporation-coating glass layer is structured by comprises local etching following the coating operation.
- 21. (Currently amended) The process as claimed in one of the preceding claims, wherein claim 3, further comprising moving the metallic substrate is moved with respect to the a coating source during the coating operation depositing step.
- 22. (Currently amended) The process as claimed in one of the preceding claims claim 3, wherein the step of coating with an depositing the hermetic evaporation-coating glass layer comprises plasma ion assisted deposition (PIAD).
- 23. (Currently amended) A coated substrate, in particular producible by the process as claimed in one of the preceding claims, which comprises comprising:
- at least one metallic surface, wherein the substrate is provided with; and
- at least one evaporation-coating glass layer on the $\underline{\text{at}}$ least one metallic surface.
- 24. (Currently amended) The coated substrate as claimed in claim 23, wherein the <u>at least one</u> evaporation-coating glass layer comprises a structured coating.

- 25. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the substrate has a multilayer coating with at least one evaporation-coating glass layer comprises at least two evaporation-coating glass layers.
- 26. (Original) The coated substrate as claimed in claim 25, wherein the at least two evaporation-coating glass layers have different compositions.
- 27. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the at least one evaporation-coating glass layer has a thickness in the range from 0.01 μ m to 1 mm.
- 28. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the surface roughness of the coated metallic surface at least one evaporation-coating glass layer has a surface roughness that is less than or equal to 50 μm.
- 29. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the substrate at least one metallic surface comprises a solid metal substrate or a composite material substrate.
- 30. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the at least one evaporation-coating glass layer has a composition which that varies in the a direction perpendicular to the coated at least one metallic surface.

- 31. (Currently amended) The coated substrate as claimed in one of the preceding claims claim 23, wherein the at least one metallic surface is not planar, for example is curved or stepped.
 - 32. Cancelled